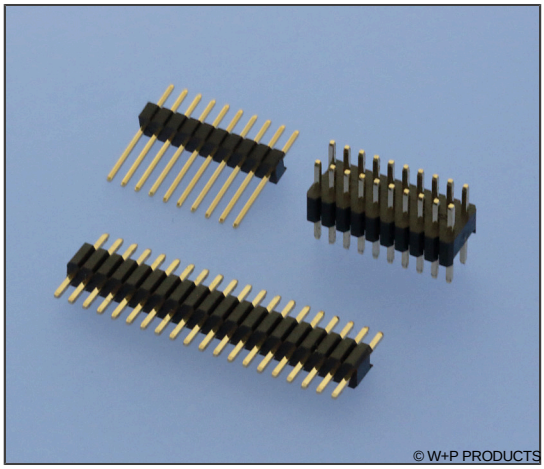
46-702 / 46-703

Stiftleisten RM 1,27x2,54mm, gerade, 1-/2-reihig

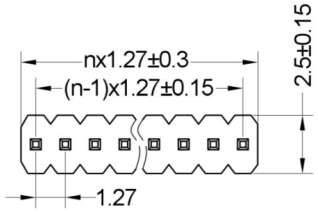
Pin Headers, 1.27x2.54mm Pitch, Straight, Single/Double Row

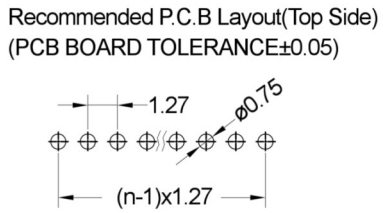
Technische Daten / *Technical Data*

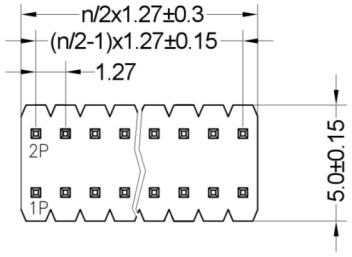
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Au über Ni
Contact Surface	*Au over Ni*
RoHS-Ausnahmen 6a-I / 6c	keine
RoHS Exemptions 6a-I / 6c	*none*
Durchgangswiderstand	< 20 mΩ
Contact Resistance	*< 20 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	500 V AC/DC
Test Voltage	*500 V AC/DC*
Nennstrom	1 A
Current Rating	*1 A*
Temperaturbereich	-40 °C ... +105 °C
Temperature Range	*-40 °C ... +105 °C*
Verarbeitung	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden)
Processing	*230 °C for 30-60 seconds (260 °C for 10 seconds)*

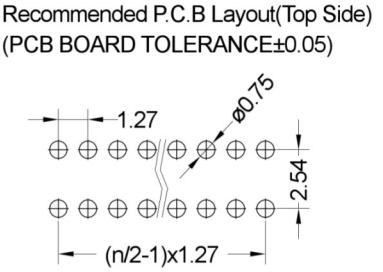


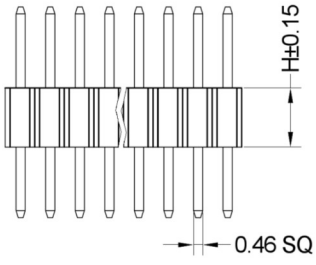
Passende Buchsenleisten:
Compatible Female Headers:
46-709 46-710

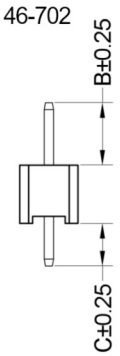


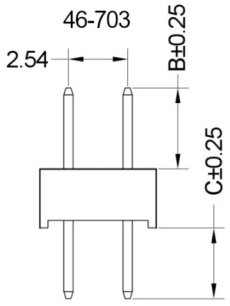












Series*	***Contacts****	***Dimensions****	***Plating***
46-702	**010**	**10**	**00**
46-702 Einreihig *Single row* **46-703** Zweireihig *Double row*	**002-020** Einreihig (Dim. 10+20) *Single row (Dim. 10+20)* **002-050** Einreihig (Dim. 30+40) *Single row (Dim. 30+40)* **004-100** Zweireihig *Double row*	Einreihig: *Single row:* **10** B=2,80 C=2,60 H=1,70mm **20** B=6,00 C=3,00 H=1,70mm **30** B=2,80 C=2,60 H=2,50mm **40** B=6,00 C=3,00 H=2,50mm Zweireihig: *Double row:* **50** B=2,80 C=2,60 H=2,50mm **60** B=6,00 C=3,00 H=2,50mm	**00** Vergoldet *Gold plated*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Reflow-Lötverfahren
Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*Lower Temperature [°C]*
Duration above T_L	*Acc. to datasheet [sec]*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*Upper Temperature [°C]*
Duration Peak Temperature	*Acc. to datasheet [sec]*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*